

Features

- **Function, pinout, and drive compatible with FCT, and F logic**
- **FCT-D speed at 3.8 ns max. (Com'l), FCT-C speed at 4.1 ns max. (Com'l), FCT-A speed at 4.6 ns max. (Com'l)**
- **Reduced V_{OH} (typically = 3.3V) versions of equivalent FCT functions**
- **Edge-rate control circuitry for significantly improved noise characteristics**
- **Power-off disable feature**
- **ESD > 2000V**
- **Matched rise and fall times**
- **Fully compatible with TTL input and output logic levels**
- **Extended commercial range of -40°C to $+85^{\circ}\text{C}$**
- **Sink current 64 mA (Com'l), 48 mA (Mil)**
- **Source current 32 mA (Com'l), 12 mA (Mil)**

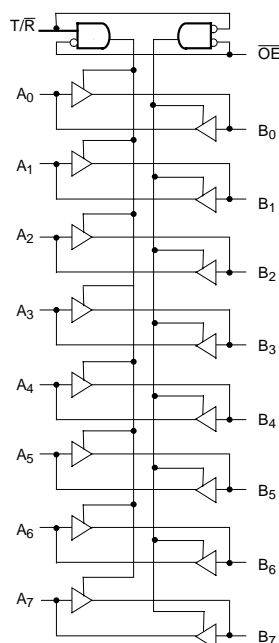
Functional Description

The FCT245T contains eight non-inverting bidirectional buffers with three-state outputs and is intended for bus oriented applications. For the FCT245T, current sinking capability is 64 mA at the A and B ports.

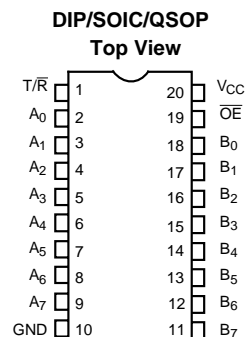
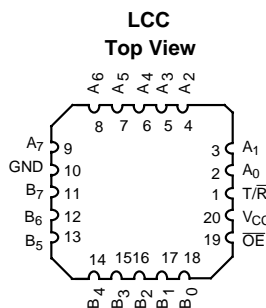
The Transmit/Receiver (T/\bar{R}) input determines the direction of data flow through bidirectional transceiver. Transmit (Active HIGH) enables data from A ports to B ports. The output enable (\overline{OE}), when HIGH, disables both the A and B ports by putting them in a High Z condition.

The outputs are designed with a power-off disable feature to allow for live insertion of boards.

Logic Block Diagram



Pin Configurations



Function Table^[1]

\overline{OE}	T/\bar{R}	Operation
L	L	B Data to Bus A
L	H	A Data to Bus B
H	X	High Z State

Note:

1. H = HIGH Voltage Level. L = LOW Voltage Level. X = Don't Care.

Maximum Ratings^[2,3]

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature	-65°C to +150°C
Ambient Temperature with Power Applied	-65°C to +135°C
Supply Voltage to Ground Potential.....	-0.5V to +7.0V
DC Input Voltage	-0.5V to +7.0V
DC Output Voltage	-0.5V to +7.0V
DC Output Current (Maximum Sink Current/Pin).....	120 mA

Power Dissipation	0.5W
Static Discharge Voltage.....	>2001V (per MIL-STD-883, Method 3015)

Operating Range

Range	Range	Ambient Temperature	V _{CC}
Commercial	DT	0°C to +70°C	5V ± 5%
Commercial	T, AT, CT	-40°C to +85°C	5V ± 5%
Military ^[4]	All	-55°C to +125°C	5V ± 10%

Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions	Min.	Typ. ^[5]	Max.	Unit	
V _{OH}	Output HIGH Voltage	V _{CC} =Min., I _{OH} =-32 mA	Com'l	2.0		V	
		V _{CC} =Min., I _{OH} =-15 mA	Com'l	2.4	3.3	V	
		V _{CC} =Min., I _{OH} =-12 mA	Mil	2.4	3.3	V	
V _{OL}	Output LOW Voltage	V _{CC} =Min., I _{OL} =64 mA	Com'l		0.3	0.55	V
		V _{CC} =Min., I _{OL} =48mA	Mil		0.3	0.55	V
V _{IH}	Input HIGH Voltage		2.0			V	
V _{IL}	Input LOW Voltage				0.8	V	
V _H	Hysteresis ^[6]	All inputs		0.2		V	
V _{IK}	Input Clamp Diode Voltage	V _{CC} =Min., I _{IN} =-18 mA		-0.7	-1.2	V	
I _I	Input HIGH Current	V _{CC} =Max., V _{IN} =V _{CC}			5	μA	
I _{IH}	Input HIGH Current	V _{CC} =Max., V _{IN} =2.7V			±1	μA	
I _{IL}	Input LOW Current	V _{CC} =Max., V _{IN} =0.5V			±1	μA	
I _{OS}	Output Short Circuit Current ^[7]	V _{CC} =Max., V _{OUT} =0.0V	-60	-120	-225	mA	
I _{OFF}	Power-Off Disable	V _{CC} =0V, V _{OUT} =4.5V			±1	μA	

Capacitance^[6]

Parameter	Description	Typ. ^[5]	Max.	Unit
C _{IN}	Input Capacitance	5	10	pF
C _{OUT}	Output Capacitance	9	12	pF

Notes:

- Unless otherwise noted, these limits are over the operating free-air temperature range.
- Unused inputs must always be connected to an appropriate logic voltage level, preferably either V_{CC} or ground.
- T_A is the "instant on" case temperature.
- Typical values are at V_{CC}=5.0V, T_A=+25°C ambient.
- This parameter is specified but not tested.
- Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample and hold techniques are preferable in order to minimize internal chip heating and more accurately reflect operational values. Otherwise prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parametric tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

Power Supply Characteristics

Parameter	Description	Test Conditions	Typ. ^[5]	Max.	Unit
I_{CC}	Quiescent Power Supply Current	$V_{CC}=\text{Max.}, V_{IN}\leq 0.2\text{V}, V_{IN}\geq V_{CC}-0.2\text{V}$	0.1	0.2	mA
ΔI_{CC}	Quiescent Power Supply Current (TTL inputs HIGH)	$V_{CC}=\text{Max.}, V_{IN}=3.4\text{V},^{[8]}$ $f_1=0, \text{Outputs Open}$	0.5	2.0	mA
I_{CCD}	Dynamic Power Supply Current ^[9]	$V_{CC}=\text{Max.}, \text{One Input Toggling,}$ $50\% \text{ Duty Cycle, Outputs Open,}$ $T/\bar{R} \text{ or } \bar{O}\bar{E}=\text{GND and}$ $V_{IN}\leq 0.2\text{V or } V_{IN}\geq V_{CC}-0.2\text{V}$	0.06	0.12	mA/MHz
I_C	Total Power Supply Current ^[10]	$V_{CC}=\text{Max.}, 50\% \text{ Duty Cycle, Outputs Open,}$ $\text{One Bit Toggling at } f_1=10 \text{ MHz,}$ $T/\bar{R} \text{ or } \bar{O}\bar{E}=\text{GND and}$ $V_{IN}\leq 0.2\text{V or } V_{IN}\geq V_{CC}-0.2\text{V}$	0.7	1.4	mA
		$V_{CC}=\text{Max.}, 50\% \text{ Duty Cycle, Outputs Open,}$ $\text{One Bit Toggling at } f_1=10 \text{ MHz,}$ $T/\bar{R} \text{ or } \bar{O}\bar{E}=\text{GND and } V_{IN}=3.4\text{V or } V_{IN}=\text{GND}$	1.2	3.4	mA
		$V_{CC}=\text{Max.}, 50\% \text{ Duty Cycle, Outputs Open,}$ $\text{Eight Bits Toggling at } f_1=2.5 \text{ MHz,}$ $T/\bar{R} \text{ or } \bar{O}\bar{E}=\text{GND and}$ $V_{IN}\leq 0.2\text{V or } V_{IN}\geq V_{CC}-0.2\text{V}$	1.3	2.6 ^[11]	mA
		$V_{CC}=\text{Max.}, 50\% \text{ Duty Cycle, Outputs Open,}$ $\text{Eight Bits Toggling at } f_1=2.5 \text{ MHz,}$ $T/\bar{R} \text{ or } \bar{O}\bar{E}=\text{GND and } V_{IN}=3.4\text{V or } V_{IN}=\text{GND}$	3.3	10.6 ^[11]	mA

Notes:

8. Per TTL driven input ($V_{IN}=3.4\text{V}$); all other inputs at V_{CC} or GND.
9. This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
10. $I_C = I_{\text{QUIESCENT}} + I_{\text{INPUTS}} + I_{\text{DYNAMIC}}$
 $I_C = I_{CC} + \Delta I_{CC} D_H N_T + I_{CCD} (f_0/2 + f_1 N_1)$
 I_{CC} = Quiescent Current with CMOS input levels
 ΔI_{CC} = Power Supply Current for a TTL HIGH input ($V_{IN}=3.4\text{V}$)
 D_H = Duty Cycle for TTL inputs HIGH
 N_T = Number of TTL inputs at D_H
 I_{CCD} = Dynamic Current caused by an input transition pair (HLH or LHL)
 f_0 = Clock frequency for registered devices, otherwise zero
 f_1 = Input signal frequency
 N_1 = Number of inputs changing at f_1
 All currents are in milliamps and all frequencies are in megahertz.
11. Values for these conditions are examples of the I_{CC} formula. These limits are specified but not tested.

Switching Characteristics Over the Operating Range

Parameter	Description	FCT245T				FCT245AT				Unit	Fig. No. ^[13]
		Military		Commercial		Military		Commercial			
		Min. ^[12]	Max.	Min. ^[12]	Max.	Min. ^[12]	Max.	Min. ^[12]	Max.		
t _{PLH} t _{PHL}	Propagation Delay A to B or B to A	1.5	7.5	1.5	7.0	1.5	4.9	1.5	4.6	ns	1, 3
t _{PZH} t _{PZL}	Output Enable Time OE or T/R to A or B	1.5	10.0	1.5	9.5	1.5	6.5	1.5	6.2	ns	1, 7, 8
t _{PHZ} t _{PLZ}	Output Disable Time OE or T/R to A or B	1.5	10.0	1.5	7.5	1.5	6.0	1.5	5.0	ns	1, 7, 8

Switching Characteristics Over the Operating Range (continued)

Parameter	Description	FCT245CT				FCT245DT		Unit	Fig. No. ^[13]
		Military		Commercial		Commercial			
		Min. ^[12]	Max.	Min. ^[12]	Max.	Min. ^[12]	Max.		
t _{PLH} t _{PHL}	Propagation Delay A to B or B to A	1.5	4.5	1.5	4.1	1.5	3.8	ns	1, 3
t _{PZH} t _{PZL}	Output Enable Time OE or T/R to A or B	1.5	6.2	1.5	5.8	1.5	5.0	ns	1, 7, 8
t _{PHZ} t _{PLZ}	Output Disable Time OE or T/R to A or B	1.5	5.2	1.5	4.8	1.5	4.3	ns	1, 7, 8

Ordering Information

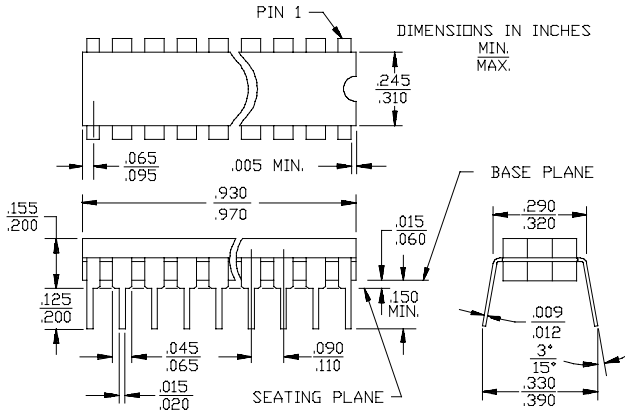
Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
3.8	CY74FCT245DTQCT	Q5	20-Lead (150-Mil) QSOP	Commercial
	CY74FCT245DTSOC/SOCT	S5	20-Lead (300-Mil) Molded SOIC	
4.1	CY74FCT245CTQCT	Q5	20-Lead (150-Mil) QSOP	Commercial
	CY74FCT245CTSOC/SOCT	S5	20-Lead (300-Mil) Molded SOIC	
4.5	CY54FCT245CTDMB	D6	20-Lead (300-Mil) CerDIP	Military
	CY54FCT245CTLMB	L61	20-Square Leadless Chip Carrier	
4.6	CY74FCT245ATPC	P5	20-Lead (300-Mil) Molded DIP	Commercial
	CY74FCT245ATQCT	Q5	20-Lead (150-Mil) QSOP	
	CY74FCT245ATSOC/SOCT	S5	20-Lead (300-Mil) Molded SOIC	
4.9	CY54FCT245ATDMB	D6	20-Lead (300-Mil) CerDIP	Military
	CY54FCT245ATLMB	L61	20-Square Leadless Chip Carrier	
7.0	CY74FCT245TQCT	Q5	20-Lead (150-Mil) QSOP	Commercial
	CY74FCT245TSOC/SOCT	S5	20-Lead (300-Mil) Molded SOIC	
7.5	CY54FCT245TDMB	D6	20-Lead (300-Mil) CerDIP	Military
	CY54FCT245TLMB	L61	20-Square Leadless Chip Carrier	

Notes:

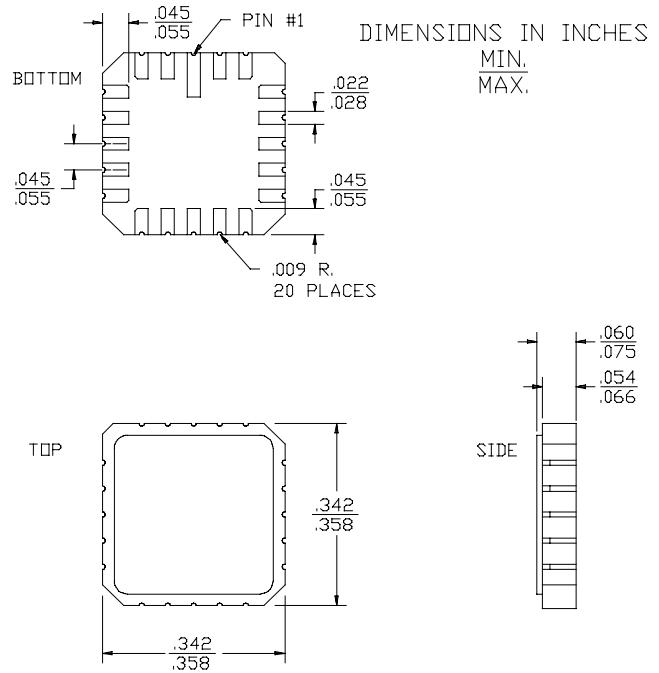
12. Minimum limits are specified but not tested on Propagation Delays.
13. See "Parameter Measurement Information" in the General Information section.

Package Diagrams

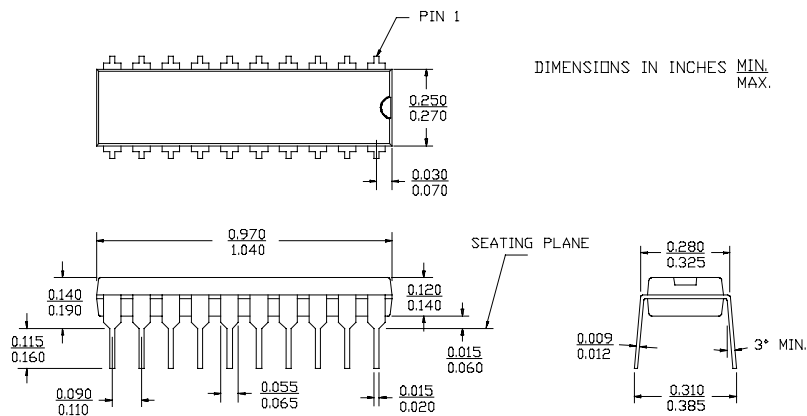
20-Lead (300-Mil) CerDIP D6
MIL-STD-1835 D-8 Config.A



20-Pin Square Leadless Chip Carrier L61
MIL-STD-1835 C-2A

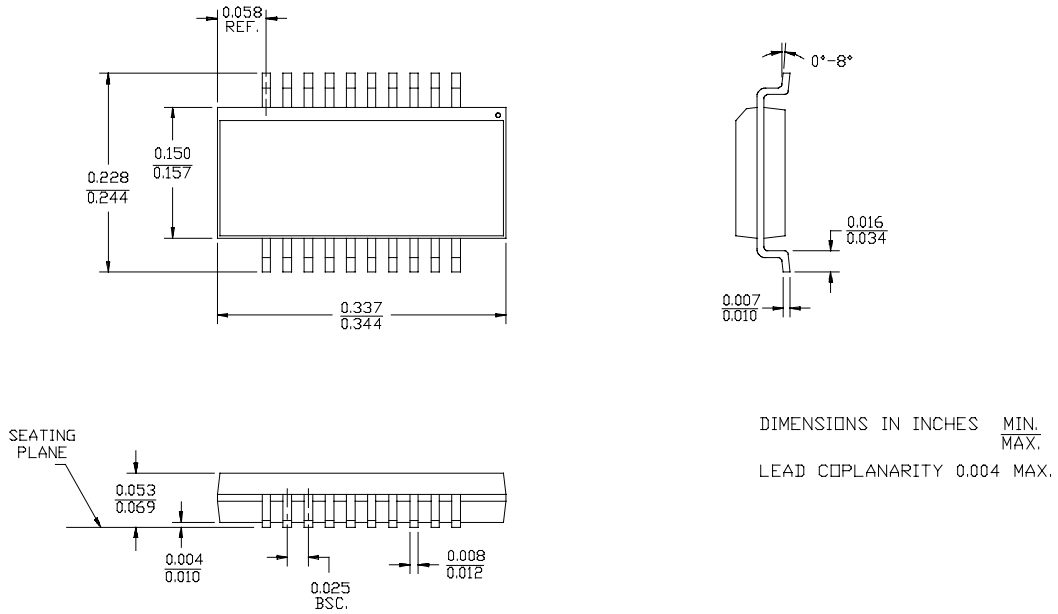


20-Lead (300-Mil) Molded DIP P5

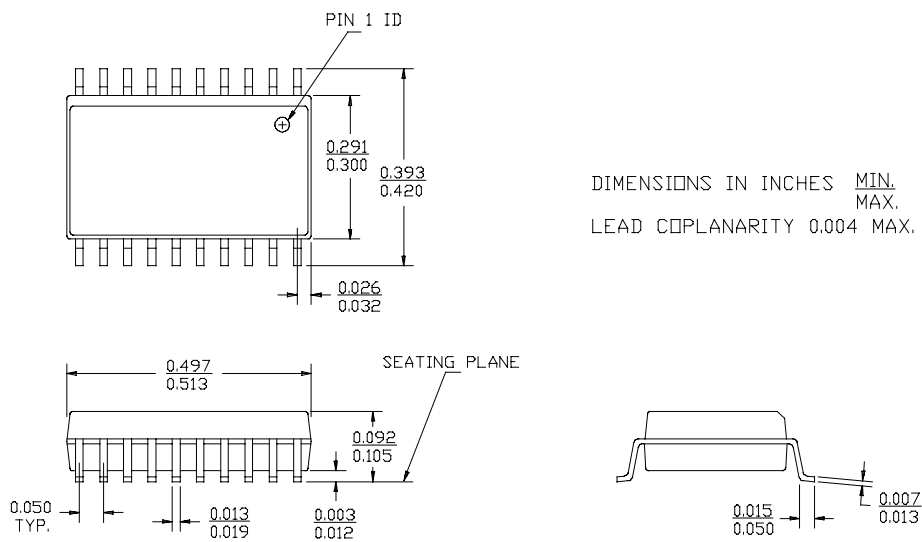


Package Diagrams (continued)

20-Lead Quarter Size Outline Q5



20-Lead (300-Mil) Molded SOIC S5



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